

LB E6SG

Power TOPLED®

PowerTOPLED, a powerful member of the TOPLED family. Thanks to their high luminous efficacy, the LEDs are ideal for rear light clusters and indicators on vehicles and for display panels for traffic control systems.



Applications

- Cluster, Button Backlighting
- Electronic Equipment
- Interior Illumination (e.g. Ambient Map)

Features:

- Package: white PLCC-4 package, colorless clear silicone resin
- Chip technology: ThinGaN
- Typ. Radiation: 120° (Lambertian emitter)
- Color: $\lambda_{\text{dom}} = 470.0 \text{ nm}$ (● blue)
- Corrosion Robustness Class: 1B
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)

Ordering Information

Type	Luminous Intensity ¹⁾ $I_F = 30 \text{ mA}$ I_v	Ordering Code
LB E6SG-T2V1-35-46	355 ... 900 mcd	Q65112A2449

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T_{op}	min.	-40 °C
		max.	110 °C
Storage Temperature	T_{stg}	min.	-40 °C
		max.	110 °C
Junction Temperature	T_j	max.	125 °C
Junction Temperature for short time applications*	T_j	max.	175 °C
Forward current	I_F	min.	5 mA
$T_s = 25\text{ °C}$		max.	50 mA
Surge Current	I_{FS}	max.	300 mA
$t \leq 10\text{ }\mu\text{s}$; $D = 0.005$; $T_s = 25\text{ °C}$			
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}		2 kV
Reverse current ²⁾	I_R	max.	20 mA

*The median lifetime (L70/B50) for $T_j = 175\text{ °C}$ is 100h.

Characteristics

$I_F = 30 \text{ mA}$; $T_S = 25^\circ\text{C}$

Parameter	Symbol		Values
Peak Wavelength	λ_{peak}	typ.	464.0 nm
Dominant Wavelength ³⁾ $I_F = 30 \text{ mA}$	λ_{dom}	min. typ. max.	463.0 nm 470.0 nm 475.5 nm
Spectral Bandwidth at 50% $I_{\text{rel,max}}$	$\Delta\lambda$	typ.	25.0 nm
Viewing angle at 50 % I_V	2ϕ	typ.	120 °
Forward Voltage ⁴⁾ $I_F = 30 \text{ mA}$	V_F	min. typ. max.	2.90 V 3.40 V 3.80 V
Reverse voltage ²⁾ $I_R = 1 \text{ mA}$	V_R	max.	2.3 V
Reverse voltage (ESD device)	$V_{R \text{ ESD}}$	min.	12 V
Temperature Coefficient of Peak Wavelength $-10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	$TC_{\lambda_{\text{peak}}}$	typ.	0.04 nm / K
Real thermal resistance junction/solderpoint ⁵⁾	$R_{\text{thJS real}}$	max.	180 K / W

Brightness Groups

Group	Luminous Intensity ¹⁾ $I_F = 30 \text{ mA}$ min. I_v	Luminous Intensity ¹⁾ $I_F = 30 \text{ mA}$ max. I_v	Luminous Flux ⁶⁾ $I_F = 30 \text{ mA}$ typ. Φ_v
T2	355 mcd	450 mcd	1210 mlm
U1	450 mcd	560 mcd	1520 mlm
U2	560 mcd	710 mcd	1910 mlm
V1	710 mcd	900 mcd	2420 mlm

Forward Voltage Groups

Group	Forward Voltage ⁴⁾ $I_F = 30 \text{ mA}$ min. V_F	Forward Voltage ⁴⁾ $I_F = 30 \text{ mA}$ max. V_F
4	2.90 V	3.20 V
5	3.20 V	3.50 V
6	3.50 V	3.80 V

Wavelength Groups

Group	Dominant Wavelength ³⁾ $I_F = 30 \text{ mA}$ min. λ_{dom}	Dominant Wavelength ³⁾ $I_F = 30 \text{ mA}$ max. λ_{dom}
3	463.0 nm	467.0 nm
4	467.0 nm	471.0 nm
5	471.0 nm	475.5 nm

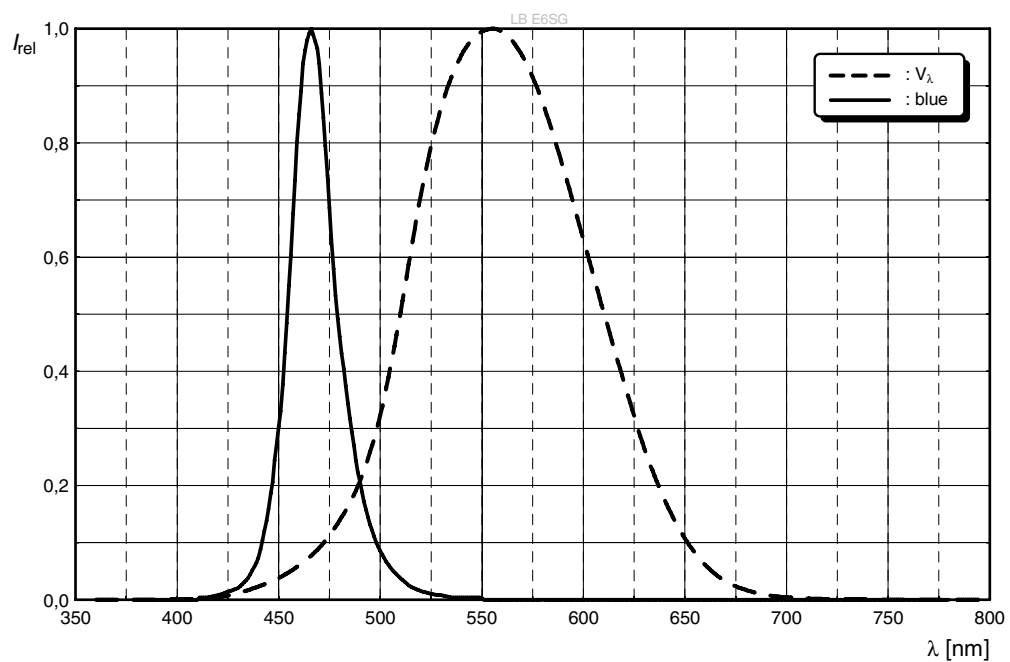
Group Name on Label

Example: T2-3-4

Brightness	Wavelength	Forward Voltage
T2	3	4

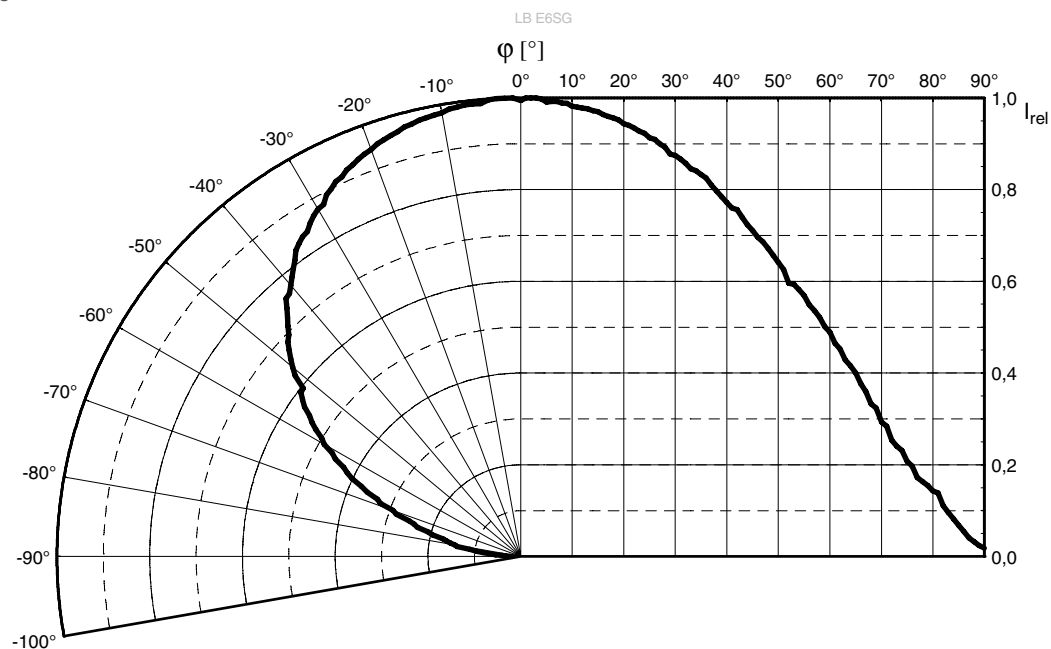
Relative Spectral Emission ⁶⁾

$I_{\text{rel}} = f(\lambda)$; $I_F = 30 \text{ mA}$; $T_S = 25^\circ\text{C}$



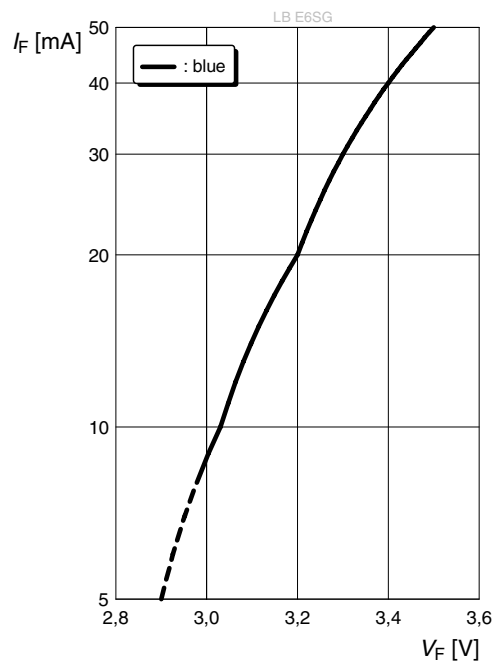
Radiation Characteristics ⁶⁾

$I_{\text{rel}} = f(\phi)$; $T_S = 25^\circ\text{C}$

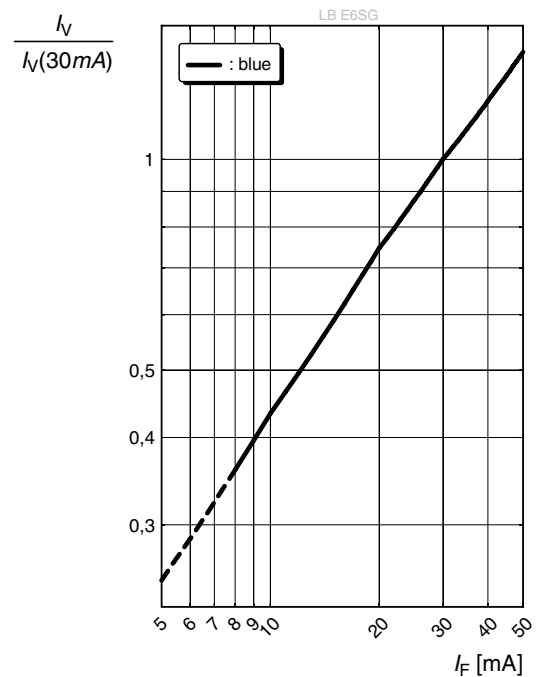


Forward current ^{6), 7)}

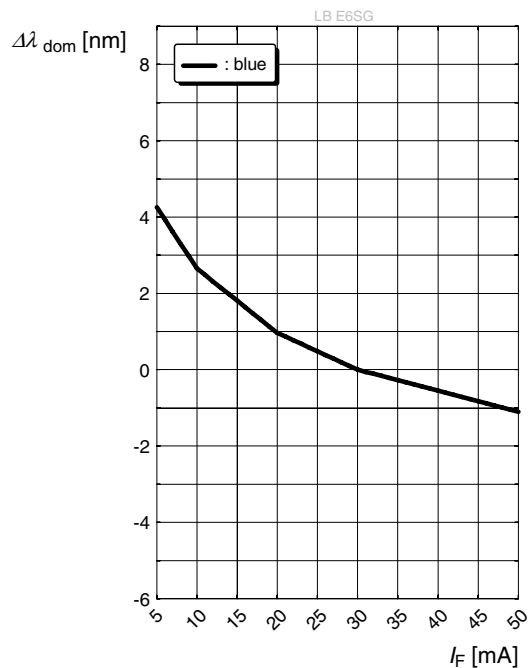
$$I_F = f(V_F); T_S = 25\text{ °C}$$

**Relative Luminous Intensity** ^{6), 7)}

$$I_V/I_V(30\text{ mA}) = f(I_F); T_S = 25\text{ °C}$$

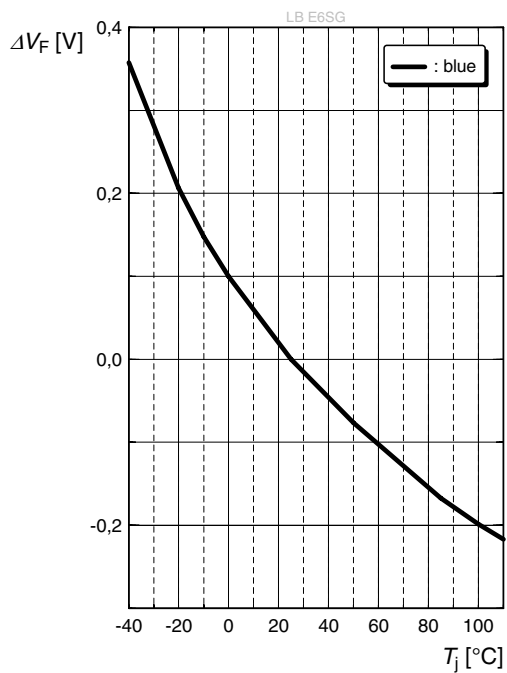
**Dominant Wavelength** ⁶⁾

$$\Delta\lambda_{\text{dom}} = f(I_F); T_S = 25\text{ °C}$$

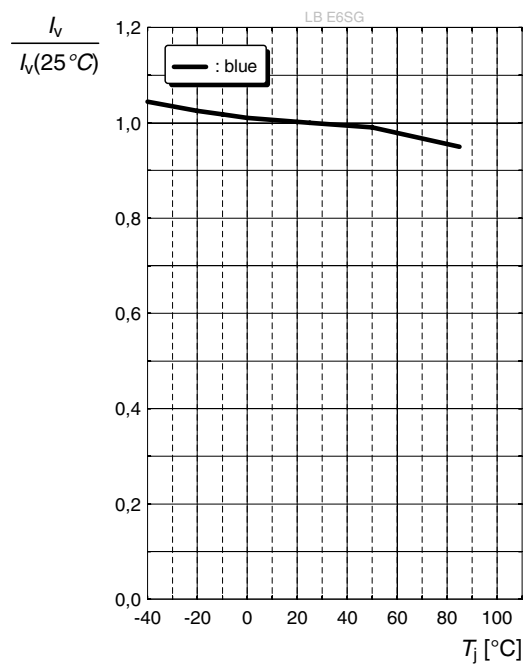


Forward Voltage ⁶⁾

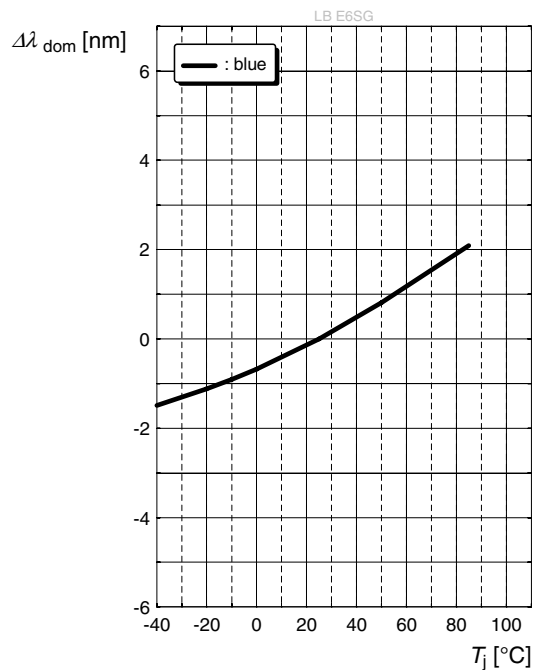
$$\Delta V_F = V_F - V_F(25^\circ\text{C}) = f(T_j); I_F = 30\text{ mA}$$

**Relative Luminous Intensity** ⁶⁾

$$I_V/I_V(25^\circ\text{C}) = f(T_j); I_F = 30\text{ mA}$$

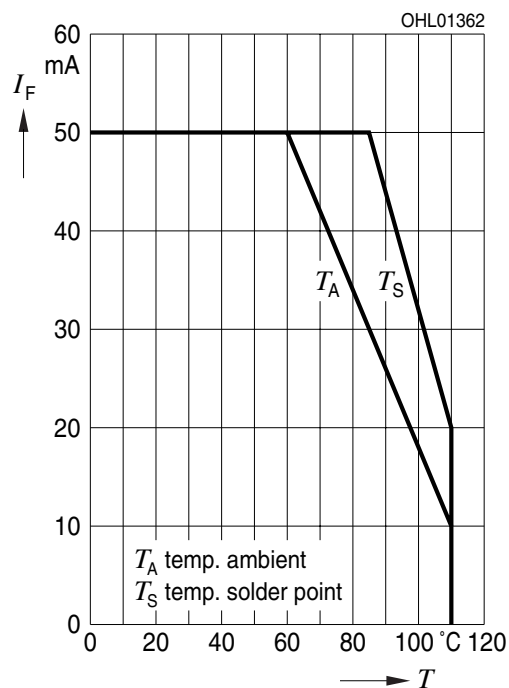
**Dominant Wavelength** ⁶⁾

$$\Delta \lambda_{\text{dom}} = \lambda_{\text{dom}} - \lambda_{\text{dom}}(25^\circ\text{C}) = f(T_j); I_F = 30\text{ mA}$$



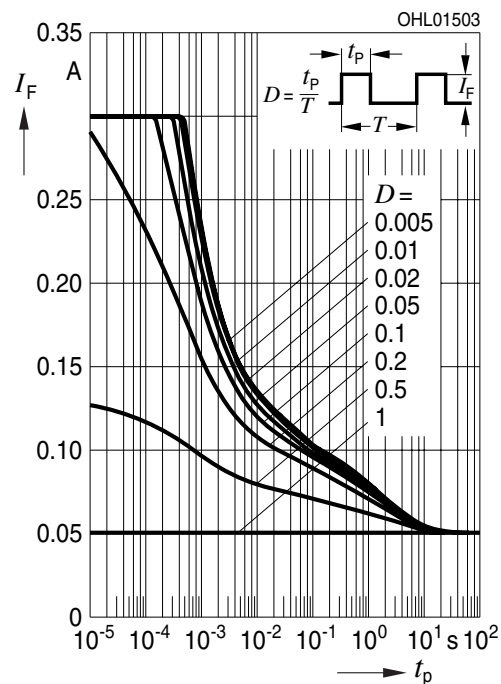
Max. Permissible Forward Current

$$I_F = f(T)$$



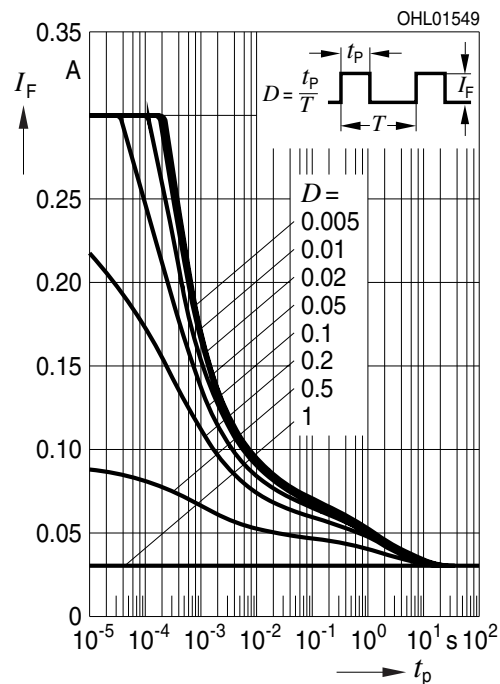
Permissible Pulse Handling Capability

$$I_F = f(t_p); D: \text{Duty cycle}; T_S = 25^\circ\text{C}$$

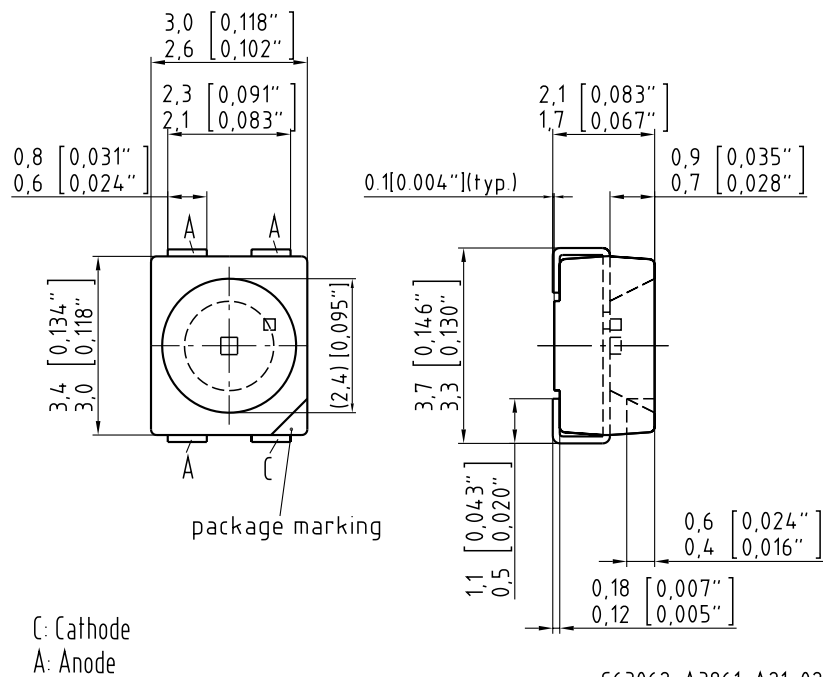


Permissible Pulse Handling Capability

$$I_F = f(t_p); D: \text{Duty cycle}; T_S = 85^\circ\text{C}$$



Dimensional Drawing ⁸⁾



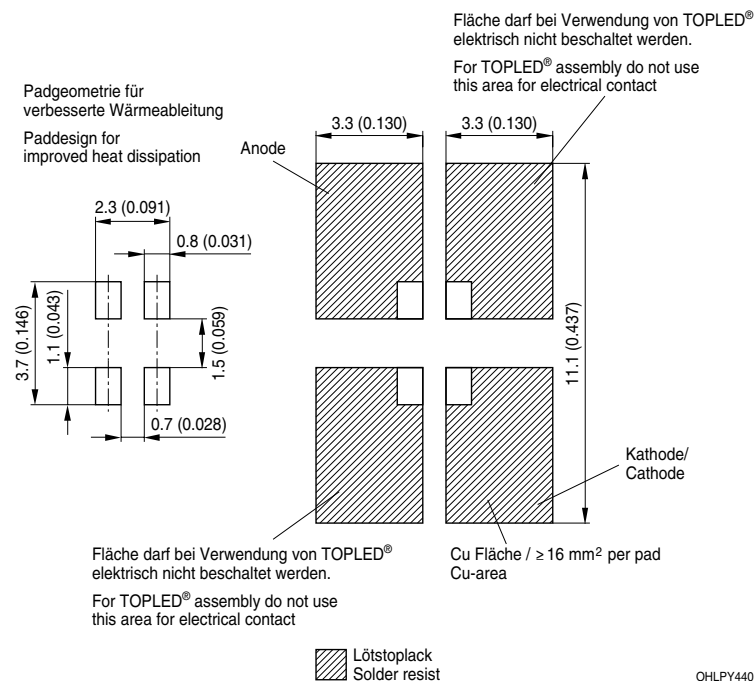
Approximate Weight: 30.0 mg

Package marking: Cathode

Corrosion test: Class: 1B
Test condition: 25°C / 75 % RH / 200ppb SO₂, 200ppb NO₂, 10ppb H₂S, 10ppb Cl₂ / 21 days (EN 60068-2-60 (Method 4))

ESD advice: The device is protected by ESD device which is connected in parallel to the Chip.

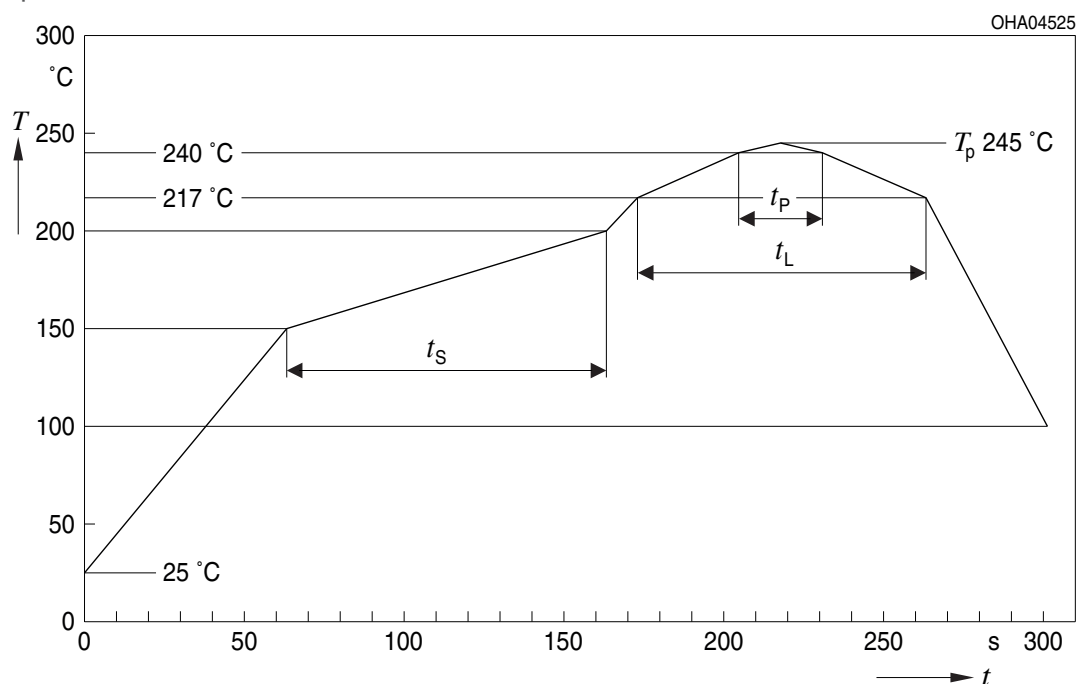
Recommended Solder Pad ⁸⁾



For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

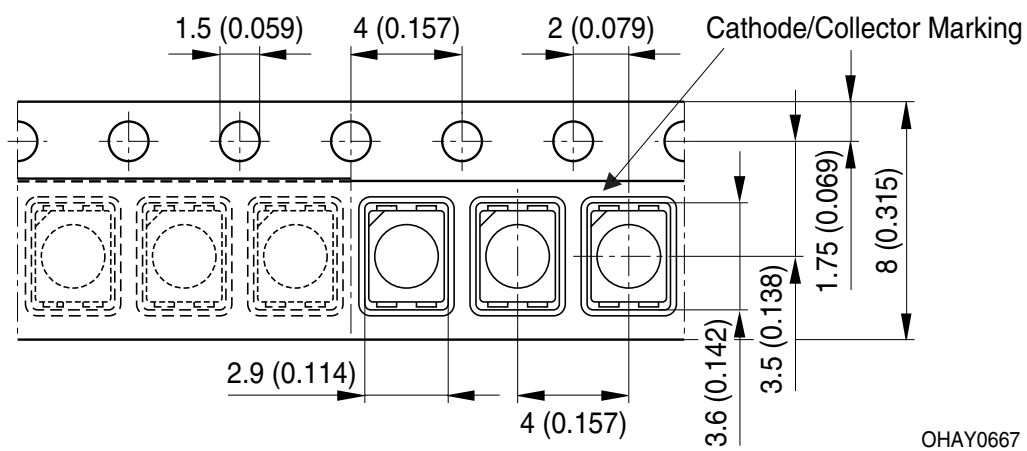
Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



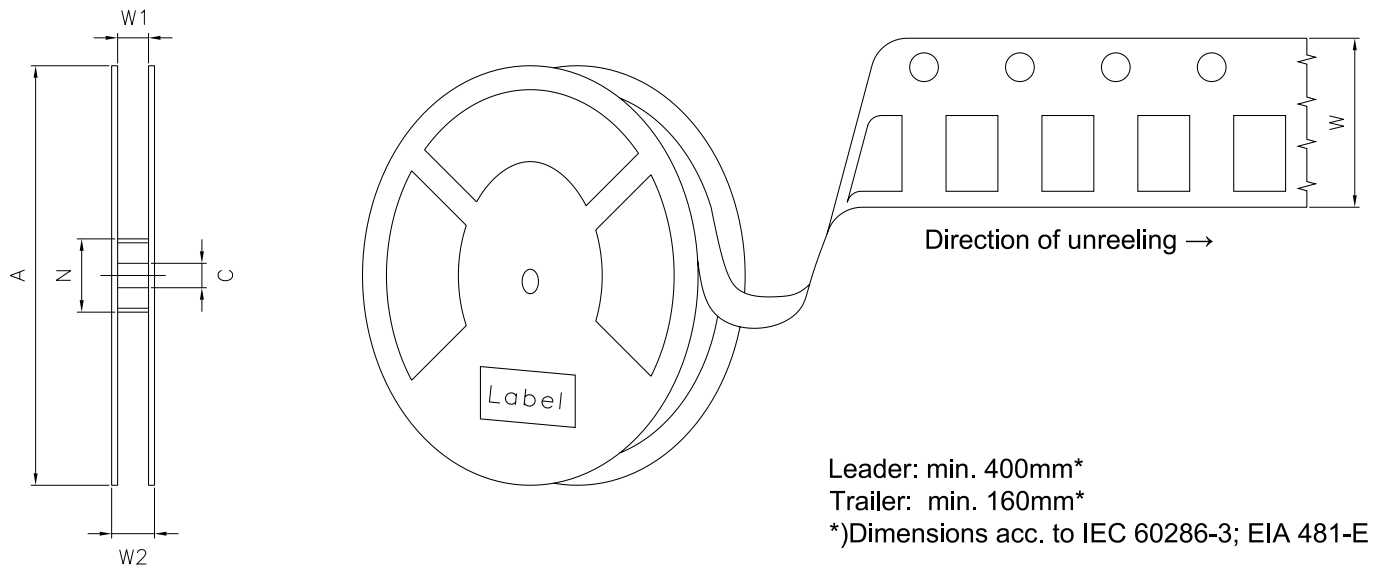
Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t_s	60	100	120	s
Ramp-up rate to peak*) T_{Smax} to T_p			2	3	K/s
Liquidus temperature	T_L		217		$^{\circ}\text{C}$
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_p		245	260	$^{\circ}\text{C}$
Time within 5 °C of the specified peak temperature $T_p - 5\text{ K}$	t_p	10	20	30	s
Ramp-down rate* T_p to 100 °C			3	6	K/s
Time 25 °C to T_p				480	s

All temperatures refer to the center of the package, measured on the top of the component

* slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

Taping ⁸⁾

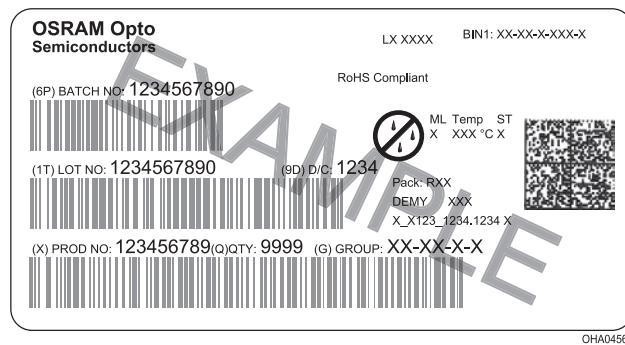
Tape and Reel ⁹⁾



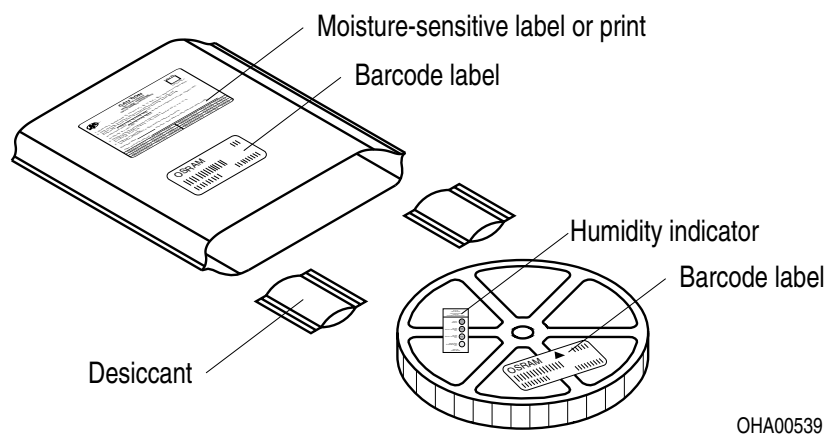
Reel dimensions [mm]

A	W	N _{min}	W ₁	W _{2 max}	Pieces per PU
180 mm	8 + 0.3 / - 0.1	60	8.4 + 2	14.4	2000
330 mm	8 + 0.3 / - 0.1	60	8.4 + 2	14.4	8000

Barcode-Product-Label (BPL)

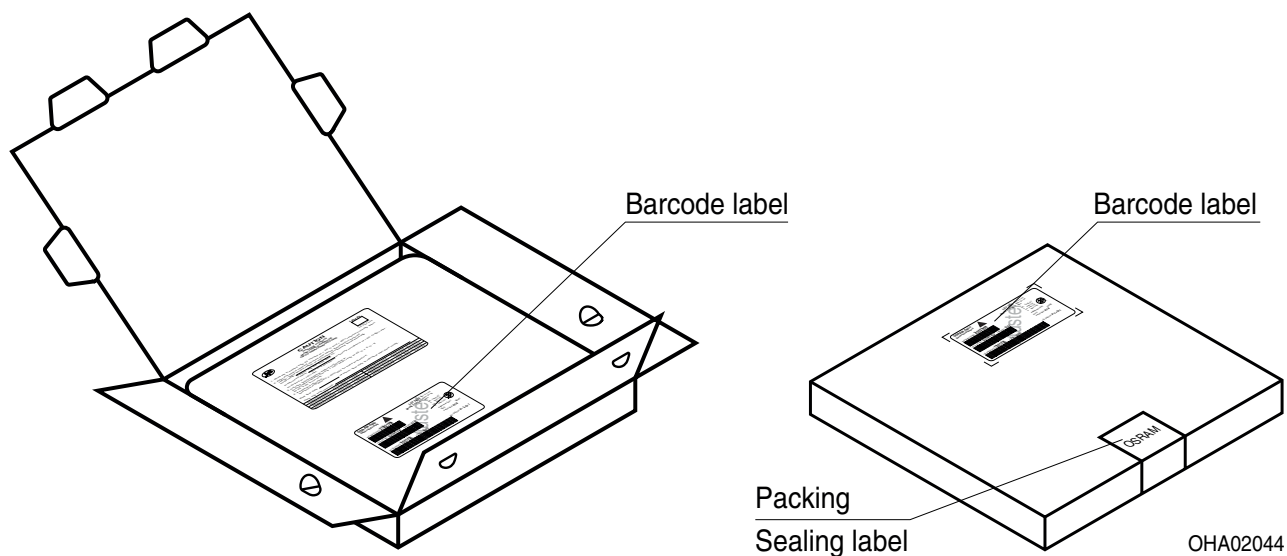


Dry Packing Process and Materials ⁸⁾



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Transportation Packing and Materials ⁸⁾



Dimensions of transportation box in mm

Width	Length	Height
200 ± 5 mm	195 ± 5 mm	30 ± 5 mm
352 ± 5 mm	352 ± 5 mm	33 ± 5 mm

Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this LED contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize LED exposure to aggressive substances during storage, production, and use. LEDs that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related informations please visit www.osram-os.com/appnotes

Disclaimer

Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

In case Buyer – or Customer supplied by Buyer– considers using OSRAM OS components in product safety devices/applications or medical devices/applications, Buyer and/or Customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and Buyer and /or Customer will analyze and coordinate the customer-specific request between OSRAM OS and Buyer and/or Customer.

Glossary

- 1) **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of $\pm 8\%$ and an expanded uncertainty of $\pm 11\%$ (acc. to GUM with a coverage factor of $k = 3$).
- 2) **Reverse Operation:** Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed. ESD device will show visible radiation (emission color red) during reverse operation of the device.
- 3) **Wavelength:** The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of $\pm 0.5\text{ nm}$ and an expanded uncertainty of $\pm 1\text{ nm}$ (acc. to GUM with a coverage factor of $k = 3$).
- 4) **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of $\pm 0.05\text{ V}$ and an expanded uncertainty of $\pm 0.1\text{ V}$ (acc. to GUM with a coverage factor of $k = 3$).
- 5) **Thermal Resistance:** $R_{th\text{ max}}$ is based on statistic values (6σ).
- 6) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 7) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 8) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.
- 9) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

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EU RoHS and China RoHS compliant product



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按照中国的相关法规和标准，不含有毒有害物质或元素。